

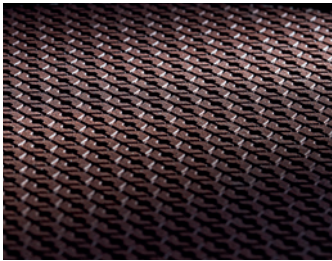
Polishing pads

Composite polishing pad, copper-resin matrix

**IRINO-PRO-C**

**Composite polishing pad for lapping and polishing of Sapphire, SiC and technical ceramic**

The novel IRINO-PRO-C composite polishing pad is closing the gap between lapping on metal plates and polishing on pads. It is most suitable for lapping and polishing of superhard materials such as sapphire, SiC, tungsten carbide and ceramics. Combined with application-tailored diamond suspensions from Pureon, IRINO-PRO-C allows for high surface qualities and impressive stock removal rates at the same time. The polishing pad comes with a self-adhesive backing. As such, it can be applied to any existing metal carrier plate, which makes it very user-friendly.

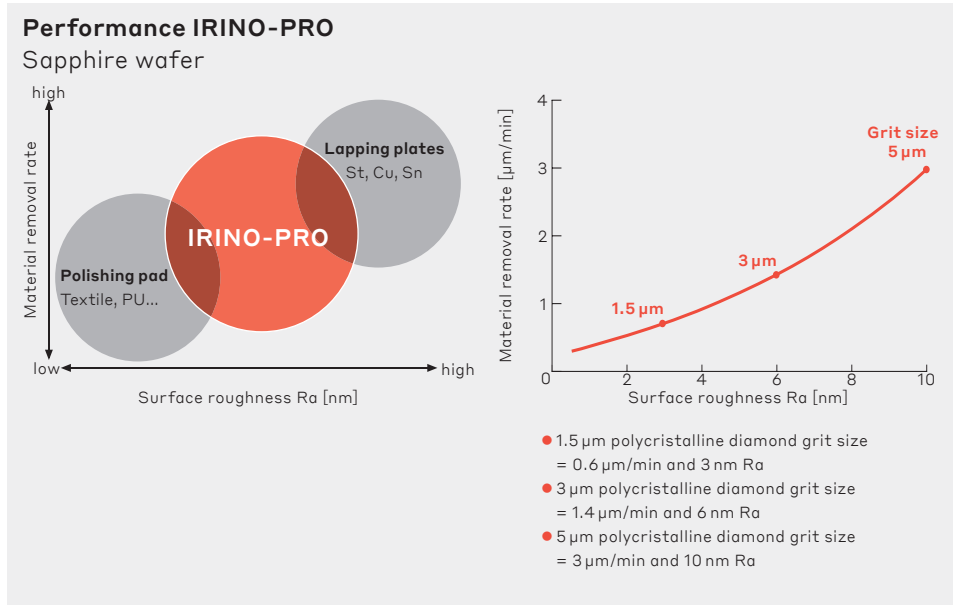


**Product specifications**

- Medium-hard bonding
- Matrix.....Copper resin
- Base .....Polycarbonate, self-adhesive backing
- Hardness .....60 – 65 Shore D
- Layer thickness.....1.0 or 1.6 mm
- Diameter .....200 – 760 mm one-piece, larger than 760 mm multi-piece
- Applications .....Stock removal or polishing of sapphire and ceramics



IRINO-PRO composite polishing pads are used with diamond suspensions. Application-tailored, stabilized diamond suspensions with different carrier liquids can be found on [www.pureon.com/products/overview](http://www.pureon.com/products/overview). We are happy to assist you in the selection of the most suitable product.



**Contact**

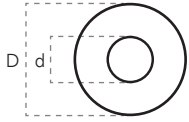
sales@pureon.com

www.pureon.com/sales-contacts

**Order information**

IRINO-PRO-C-1D265P-610×190 mm

Packing: 1 piece per box

**Diameter:**

Custom-engineered pads available on request.

**Order code**

Example: IRINO-PRO-C-(X)D **2 6 5 P** – DDD × ddd  
 ① ② ③ ④ ⑤ ⑥

① Drawing index	X optional
② Bond hardness	2 medium (60 – 65 Shore D)
③ Bond filler (metal powder)	6 with copper particles
④ Layer thickness	4 1 mm (tolerance 0 / -0.1 mm) 5 1.6 mm (tolerance 0 / -0.1 mm)
⑤ Mounting and backing	P polycarbonate (0.75 mm), self-adhesive T polycarbonate (0.75 mm), special self-adhesive
⑥ Additional order information	D outer diameter in mm d inner diameter in mm

**Highlights**

- Innovative polishing pad combines lapping and polishing principles
- Surface finishes down to 1 nm Ra
- Material removal rates similar to soft metal lapping plates
- Provides excellent workpiece geometry and flatness, without edge round-off
- Dressable system, suitable for single-side and double-side machines
- Best results if used with water-soluble or oil-based diamond suspensions from Pureon

**Design and working principle**

IRINO-PRO composite polishing pads consist of a polymer matrix with embedded metal powders. The addition of diamond suspension charges the IRINO-PRO pad with diamond particles. The embedded diamond grains facilitate stock removal on the workpiece. The continuous wear of the bonding over its service life prevents clogging of the pad. The patterned surface helps to improve suspension flow and exchange, even for double-sided machines.



Pureon offers a wide range of customized solutions. More information can be found on [www.pureon.com/products/overview](http://www.pureon.com/products/overview)

All information is non-binding and provided for information purposes only. Subject to change without notice.